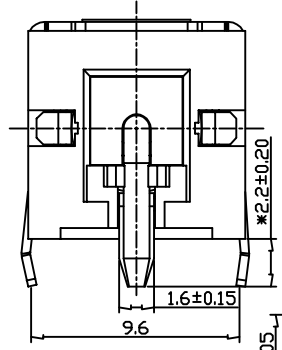
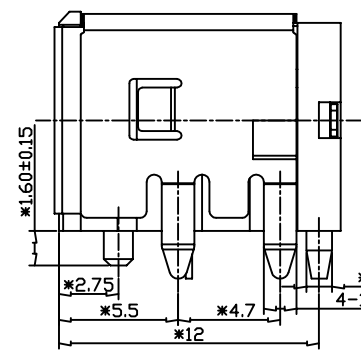
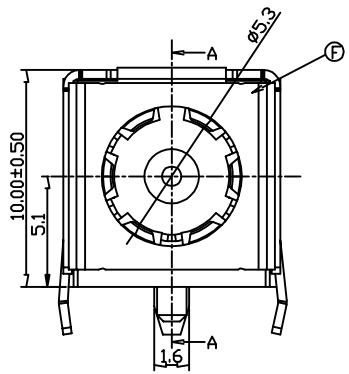
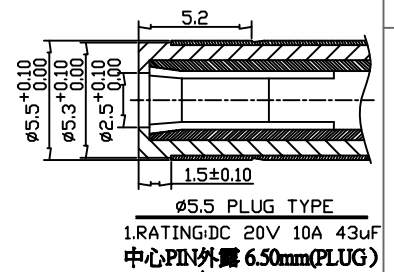
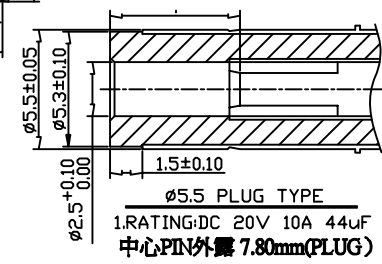
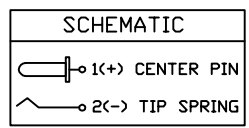
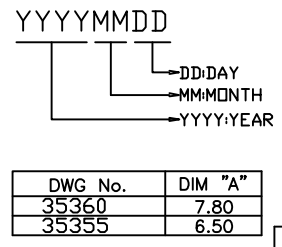
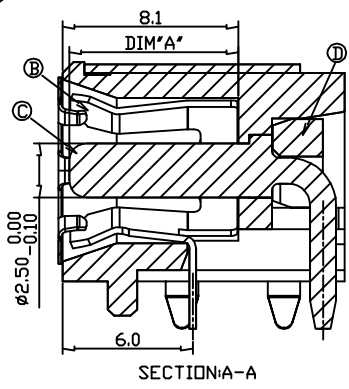
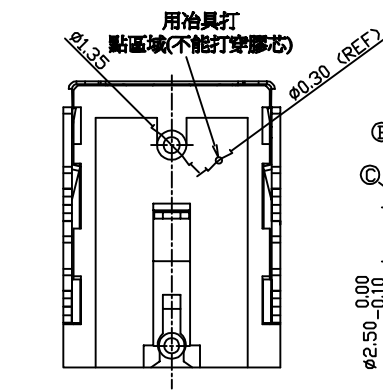


RECOMMENDED PCB LAYOUT
TOP VIEW (TOLERANCE: ±0.05)

SPECIFICATIONS:
 1. INSERTION FORCE: 3.0KG MAX. WITHDRAWAL FORCE: 1.0KG-3.0KG
 2. INSULATION RESISTANCE BETWEEN ANY ADJACENT TERMINALS SHALL NOT BE LESS THAN 100 MEGOHMS BY 500 VOLTS MEGGER
 3. JACK SHALL WITHSTAND 250 VOLTS BETWEEN ANY ADJACENT TERMINAL FOR ONE MINUTE.
 4. CONTACT RESISTANCE SHALL NOT EXCEED 30mΩ
 5. JACK SHALL WITHSTAND 5000 CYCLES OF INSERTION AND WITHDRAWAL WITH TESTING PLUG, AND CONTACT RESISTANCE SHALL NOT EXCEED 30mΩ
 6. MEASURING CONDITION:
 TEMPERATURE: FROM 5°C TO 35°C
 RELATIVE HUMIDITY: FROM 40% TO 85%
 7. ENVIRONMENTAL SPECIFICATIONS:
 7.1 HUMIDITY TEST: HUMIDITY 90% TO 95% TEMPERATURE 40°C±2°C FOR 96 HOURS
 7.2 HEAT TEST: TEMPERATURE 70°C ± 2°C (HUMIDITY BELOW 50%) FOR 96 HOURS
 7.3 COLD TEST: TEMPERATURE -40°C ± 2°C FOR 96 HOURS.
 8. PACKAGING: TRAY
 9. PRINTED DATE CODE 'YYYYMMDD' ON TOP OF CONNECTOR.
 *10. 因下板尺寸變形過大, 下板尺寸以下板為三, 注意帶*為重點檢控尺寸.



NO.	DESCRIPTION	QTY	MATERIAL	PLATING&COLOR
F	GROUND	1	STAINLESS 0.15t	N/A
E	SHELL	1	SPCC-SD 0.40t	Sn:60u" Min On Contact Area Cu:60u" Min On Solder Ni:60u"
D	STOPPER	1	HIGH TEMP. THERMOLASTIC UL 94V-0	BLACK
C	PIN	1	BRASS BAR	Ag:20u" Min On Contact Area Cu:60u" Min On Solder Ni:60u"
B	SPRING	1	COPPER ALLOY 0.30t	Sn:60u" Min On Contact Area Cu:60u" Min On Solder Ni:60u"
A	HOUSING	1	HIGH TEMP. THERMOLASTIC UL 94V-0	BLACK



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JMSCONN TECHNOLOGY CO., LTD.

PROJ	SCALE : F DO NOT SCALE DWG	MOLD NO	35355	
APP		MODEL	FILE NO	REV. X1
CHK		DGN		
DRW	HSIEH	2016.11.18	UNIT MM	SHT 1 OF 1 SIZE A4